# **Dual Buffer with 3-State Outputs**

The NL27WZ125 is a high performance dual noninverting buffer operating from a 1.65 V to 5.5 V supply.

# **Features**

- Extremely High Speed:  $t_{PD}$  2.6 ns (typical) at  $V_{CC} = 5 \text{ V}$
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- Over Voltage Tolerant Inputs and Outputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with  $V_{CC}$  = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- 3-State OE Input is Active-Low
- Replacement for NC7WZ125
- Chip Complexity = 72 FETs
- These Devices are Pb-Free and are RoHS Compliant

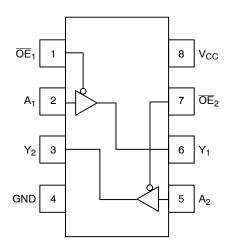


Figure 1. Pinout (Top View)

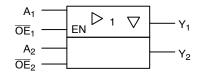


Figure 2. Logic Symbol

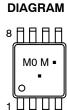


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US8 US SUFFIX CASE 493



**MARKING** 

M0 = Device Code
M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

# **PIN ASSIGNMENT**

Pin	Function
1	ŌE <sub>1</sub>
2	A <sub>1</sub>
3	Y <sub>2</sub>
4	GND
5	A <sub>2</sub>
6	Y <sub>1</sub>
7	OE <sub>2</sub>
8	V <sub>CC</sub>

# **FUNCTION TABLE**

In	Output	
ŌĒ <sub>n</sub> A <sub>n</sub>		Yn
L	L	L
L	Н	Н
Н	Х	Z

X = Don't Caren = 1, 2

# ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# **MAXIMUM RATINGS**

Symbol	Parameter	Value	Units
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	-0.5 to +7.0	V
V <sub>O</sub>	DC Output Voltage Output in High Impedance State Output in HIGH or LOW State	-0.5 to +7.0 -0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current, V <sub>I</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current, V <sub>O</sub> < GND	-50	mA
Io	DC Output Sink Current	±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature under Bias	+150	°C
$\theta_{JA}$	Thermal Resistance (Note 1)	250	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating - Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Units
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage (Note 6)	0	5.5	V
Vo	Output Voltage (HIGH or LOW State)	0	5.5	V
T <sub>A</sub>	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate     V <sub>CC</sub> = 2.5 V ±0.2 V     V <sub>CC</sub> = 3.0 V ±0.3 V     V <sub>CC</sub> = 5.0 V ±0.5 V	0 0 0	20 10 5	ns/V

<sup>6.</sup> Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

# **DEVICE ORDERING INFORMATION**

Device Order Number	Package Type	Shipping <sup>†</sup>
NL27WZ125USG	US8 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# DC ELECTRICAL CHARACTERISTICS

			$V_{CC}$ $T_{A} = 25^{\circ}C$ $-55^{\circ}C \le T_{A} \le 125^{\circ}C$		T <sub>A</sub> = 25°C		A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V <sub>IH</sub>	High-Level Input Voltage		1.65 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	Low-Level Input Voltage		1.65 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	High-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	$\begin{split} I_{OH} &= 100 \; \mu\text{A} \\ I_{OH} &= -3 \; \text{mA} \\ I_{OH} &= -8 \; \text{mA} \\ I_{OH} &= -12 \; \text{mA} \\ I_{OH} &= -16 \; \text{mA} \\ I_{OH} &= -24 \; \text{mA} \\ I_{OH} &= -32 \; \text{mA} \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.52 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> -0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub>	$\begin{split} I_{OL} &= 100 \; \mu\text{A} \\ I_{OL} &= 3 \; \text{mA} \\ I_{OL} &= 8 \; \text{mA} \\ I_{OL} &= 12 \; \text{mA} \\ I_{OL} &= 16 \; \text{mA} \\ I_{OL} &= 24 \; \text{mA} \\ I_{OL} &= 32 \; \text{mA} \end{split}$	2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5V or GND	0 to 5.5			±0.1		±1.0	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0			1.0		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = 5.5V or GND	5.5			1.0		10	μА
l <sub>OZ</sub>	3-State Output Leakage	$V_{IN} = V_{IL} \text{ or } V_{IH}$ $0V \le V_{OUT} \le 5.5 \text{ V}$	2.3 to 5.5			±0.5		±5	μΑ

# AC ELECTRICAL CHARACTERISTICS ( $t_R = t_F = 3.0 \text{ ns}$ )

			V <sub>CC</sub>	T <sub>A</sub> = 25°C		–55°C ≤ T	<sub>A</sub> ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay AN to YN	$R_L = 1 \text{ M}\Omega$ , $C_L = 15 \text{ pF}$	1.8 ± 0.15 2.5 ± 0.2	2.0 1.0		12 7.5	2.0 1.0	13 8	ns
	(Figures 3 and 4)	$\begin{aligned} R_L &= 1 \text{ M}\Omega, C_L = 15 \text{ pF} \\ R_L &= 500 \ \Omega, C_L = 50 \text{ pF} \end{aligned}$	3.3 ± 0.3	0.8 1.2		5.2 5.7	0.8 1.2	5.5 6.0	
		$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF $R_L$ = 500 $\Omega$ , $C_L$ = 50 pF	5.0 ± 0.5	0.5 0.8		4.5 5.0	0.5 0.8	4.8 5.3	
toslh	Output to Output Skew	$R_L = 500 \Omega$ , $C_L = 50 pF$	$3.3 \pm 0.3$			1.0		1.0	ns
TOSHL	t <sub>OSHL</sub> (Note 7)	$R_L = 500 \Omega$ , $C_L = 50 pF$	5.0 ± 0.5			0.8		0.8	
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable Time (Figures 5, 6 and 7)		1.8 ± 0.15 2.5 ± 0.2	3.0 1.8		14 8.5	3.0 1.8	15 9.0	ns
			$3.3 \pm 0.3$	1.2		6.2	1.2	6.5	
			5.0 ± 0.5	0.8		5.5	0.8	5.8	
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Enable Time (Figures 5, 6 and 7)		1.8 ± 0.15 2.5 ± 0.2	2.5 1.5		12 8.0	2.5 1.5	13 8.5	ns
			$3.3\pm0.3$	0.8		5.7	0.8	6.0	
			5.0 ± 0.5	0.3		4.7	0.3	5.0	

<sup>7.</sup> Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. This specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

# **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	7.0	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	7.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 8)	10 MHz, $V_{CC} = 3.3 \text{ V}$ , $V_{I} = 0 \text{ V or } V_{CC}$ 10 MHz, $V_{CC} = 5.5 \text{ V}$ , $V_{I} = 0 \text{ V or } V_{CC}$	18 27	pF

C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.
 Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

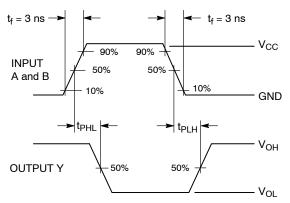
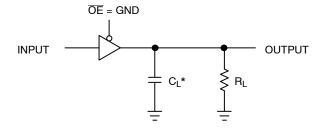


Figure 3. Switching Waveform



\*Includes all probe and jig capacitance.
A 1 MHz square input wave is recommended for propagation delay tests.

Figure 4. T<sub>PLH</sub> or T<sub>PHL</sub>

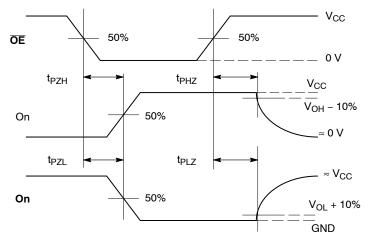
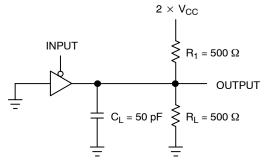
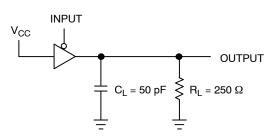


Figure 5. AC Output Enable and Disable Waveform



A 1 MHz square input wave is recommended for propagation delay tests.

Figure 6. T<sub>PZL</sub> or T<sub>PL</sub>

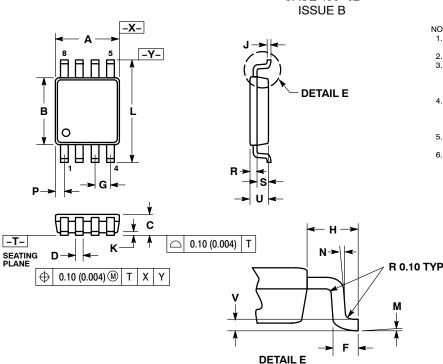


A 1 MHz square input wave is recommended for propagation delay tests.

Figure 7. T<sub>PZH</sub> or T<sub>PHZ</sub>

# PACKAGE DIMENSIONS



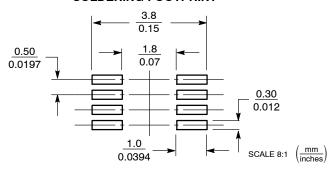


#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD
- FLASH, PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055") PER SIDE. DIMENSION "B" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION SHALL NOT E3XCEED 0.140 (0.0055") PER SIDE. LEAD FINISH IS SOLDER PLATING WITH
- THICKNESS OF 0.0076-0.0203 MM. (300-800 "). ALL TOLERANCE UNLESS OTHERWISE
- SPECIFIED ±0.0508 (0.0002 ").

	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	1.90	2.10	0.075	0.083	
В	2.20	2.40	0.087	0.094	
С	0.60	0.90	0.024	0.035	
D	0.17	0.25	0.007	0.010	
F	0.20	0.35	0.008	0.014	
G	0.50	BSC	0.020	BSC	
Н	0.40	REF	0.016	REF	
J	0.10	0.18	0.004	0.007	
K	0.00	0.10	0.000	0.004	
L	3.00	3.20	0.118	0.126	
М	0 °	6 °	0 °	6 °	
N	5 °	10 °	5 °	10 °	
P	0.23	0.34	0.010	0.013	
R	0.23	0.33	0.009	0.013	
S	0.37	0.47	0.015	0.019	
U	0.60	0.80	0.024	0.031	
V	0.12	BSC	0.005 BSC		

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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